



SEMICON India 2026 Exhibition Announcement

Takatori Corporation will exhibit at **SEMICON India 2026**, to be held from September 17 to 19, 2026.

We sincerely look forward to welcoming you to our exhibition locations.

Exhibition Highlights

【 New Model: Panel Level Packaging Machine PLP-700 】

Takatori will present its latest Panel Level Packaging machine, the **PLP-700**, designed to support panel sizes up to 700 mm × 700 mm, through panel display.

We will introduce advanced semiconductor manufacturing solutions centered on this latest PLP platform.

For detailed information about the PLP-700, please visit us at SEMICON India 2026.

【 New Model: Multi Wire Saw for 12-inch SiC MWS-SiC12F 】

【 Grinder for Superhard Materials GLP-150 】

Takatori will also present its latest multi-wire saw, the **MWS-SiC12F**, designed for slicing large-diameter ingots up to 12 inches in diameter (maximum supported diameter: 14 inches), and present Grinder for LT, SiC, AL2O3 etc., through panel displays.

For detailed information about the MWS-SiC12F, GLP-150, please visit us at SEMICON India 2026.



Exhibition Locations:
Sojitz Machinery Booth
Booth No. H4021